

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Heung-Kyu Kwon, Min-Kyo Cho
Assignee: Samsung Electronics Co., Ltd.
Title: Semiconductor Chip Package And Method Of Fabricating The Same
Serial No.: 09/464,322 Filing Date: December 15, 1999
Examiner: Chris C. Chu Group Art Unit: 2815
Docket No.: AB-881 US

San Jose, California
January 14, 2002

BOX CPA
COMMISSIONER FOR PATENTS
WASHINGTON, D. C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

This response accompanies a Continued Prosecution Application and is responsive to the September 12, 2001 Office Action and the Advisory Action having a mailing date of December 7, 2001.

IN THE CLAIMS

For the Examiner's convenience, a clean version of the entire set of pending claims is provided as follows. Claim 1 is amended and as required by 37 CFR § 1.121(c)(1)(ii), the amendment is shown in Attachment A.

3A

1. (Thrice Amended) A semiconductor chip package comprising:
a substrate having a plurality of bonding pads;
a semiconductor chip having a plurality of conductive bumps on a front side thereof,
the conductive bumps contacting the bonding pads;
a heat slug bonded to a backside of the semiconductor chip; and
a solder film directly attached to the heat slug thereby bonding the heat slug to the
backside of the semiconductor chip.

2. The semiconductor chip package of claim 1, wherein the solder film includes one selected from a group consisting of Pb, Sn, Ag, In, and Bi.

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